WHAT IS CLAIMED IS:

1. A method for wafer transfer using a polishing and loading/unloading component module, wherein the polishing and loading/unloading component module comprises a loading/unloading module in a center of the polishing and loading/unloading component module and two polishing modules, wherein one of the two polishing modules is on one side of the loading/unloading module, and another one of the two polishing modules is on another side of the loading/unloading module opposite to the one side, wherein the loading/unloading module comprises one loading/unloading table module (22), and a linear motion module (21);

the said one loading/unloading table module (22) comprises a loading/unloading stage configured for holding a wafer, and a first loading/unloading position (1) and a second loading/unloading position (6), wherein the loading/unloading stage moves between the first loading/unloading position (1) and the second loading/unloading position (6);

the linear motion module (21) comprises a sliding block, and a loading/unloading stage holder configured for positioning the loading/unloading stage of the said one loading/unloading table module (22), such that the said one loading/unloading table module (22) is fixed on the sliding block of the linear motion module (21), and the sliding block connecting the first loading/unloading position (1) and the second loading/unloading position (6) enables the said one loading/unloading table module (22) to move between the first loading/unloading position (1) and the second loading/unloading position (6),

the first loading/unloading position (1) and the second loading/unloading position (6) are in a direction perpendicular to an arrangement direction of the two polishing modules, and the method comprises following steps:

S1: the said one loading/unloading table module (22) stopping at the first loading/unloading position (1), waiting for a first polishing head (3) corresponding to the first loading/unloading position (1) and carrying a first wafer that has been polished in a first stage;

S2: after the first polishing head (3) is transferred to the first loading/unloading position (1), the

first wafer is loaded to the said one loading/unloading table module (22), and the said one loading/unloading table module (22) is moved to the second loading/unloading position (6);

S3: the first polishing head (3) being cleaned at the position above the first loading/unloading position (1), and the first wafer on the said one loading/unloading table module (22) at the second loading/unloading position (6) being loaded to a second polishing head (8) to start the polishing in a second stage, and after the second polishing head (8) is transferred above a second polishing pad (9), loading a second wafer to be polished to the said one loading/unloading table module (22);

S4: when the first polishing head (3) corresponding to the first loading/unloading position (1) being cleaned, the said one loading/unloading table module at the second loading/unloading position (6) moving to below the first polishing head (3) at the first loading/unloading position (1), and then the said one loading/unloading table module moving to above the first loading/unloading position (1), the first polishing head (3) corresponding to the first loading/unloading position (1) loading the second wafer to be polished and transferring the second wafer to be polished to a polishing area for polishing;

S5: the said one loading/unloading table module at the first loading/unloading position (1) moving to below the first loading/unloading position (1) and then moving to the second loading/unloading position (6), while the second polishing head (8) corresponding to the second loading/unloading position (6) moving to a position above the second loading/unloading position (6), the said one loading/unloading table module moving to above the second loading/unloading position (6), and loading the first wafer that has been polished in the second stage, and then the said one loading/unloading table module moving to below the second loading/unloading position (6) and moving from the second loading/unloading position (6) to the first loading/unloading position (1);

S6: the second polishing head (8) corresponding to the second loading/unloading position (6) being cleaned at the position above the second loading/unloading position (6), while removing the first wafer that has been polished in the second stage from the said one loading/unloading

table module at the first loading/unloading position (1), and the said one loading/unloading table module waiting for the second wafer that has been polished in the first stage on the first polishing head (3);

S7: after the first polishing head (3) is transferred to the first loading/unloading position (1), the said one loading/unloading table module moving to above the first loading/unloading position (1) to load the second wafer that has been polished in the first stage, and then moving to the second loading/unloading position (6);

S8: repeating the preceding steps until all wafers being polished,

wherein the polishing module comprises a fixed platform, a polishing pad, a polishing head, and a rotating shaft, the polishing pad is located on the fixed platform, and the rotating shaft drives the polishing head to rotate to at least one of the two loading/unloading positions.

2. The method according to claim 1, wherein the first loading/unloading position (1) and the second loading/unloading position (6) are respectively provided with a first nozzle module (13) and a second nozzle module (16), and both the first nozzle module (13) and the second nozzle module (16) are fixed on a fixed frame (20).

3. The method according to claim 2, wherein the first nozzle module (13) and the second nozzle module (16) are respectively arranged at edges of the first loading/unloading position (1) and the second loading/unloading position (6).

4. The method according to claim 1, wherein the loading/unloading table module (22) is moved to above or below the first loading/unloading position (1) or the second loading/unloading position (6) in a vertical direction to complete wafer transfer accompanying with a polishing head.